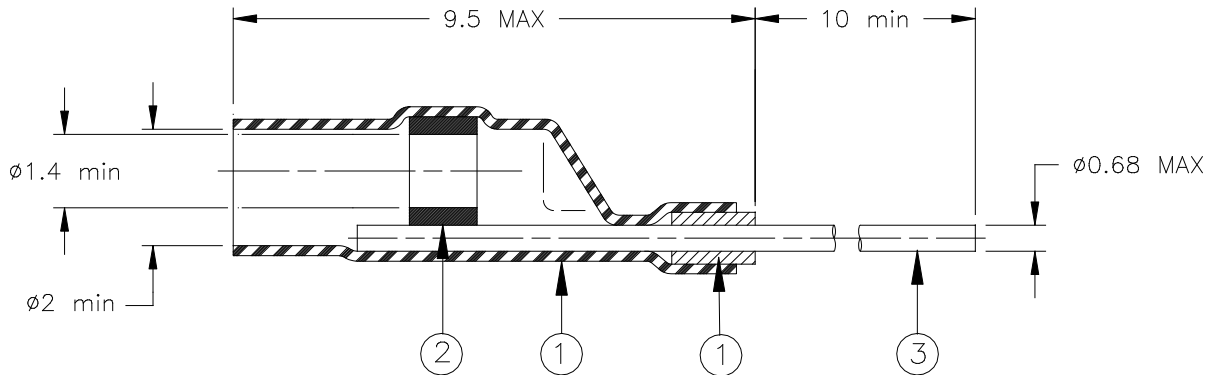


CUSTOMER DRAWING



MATERIALS


1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
SOLDER: TYPE Sn62 Pb36 Ag2 per ANSI-J-STD-006.
FLUX: TYPE ROL0 per ANSI-J-STD-004.
3. PIN: Cu/Sn-Pb/5b per ASTM B-579-73.

APPLICATION

1. This controlled soldering device is designed for attaching a tin or silver plated, stranded AWG20, 22, 24, 26, 28, and 30 wire, having an insulation rating of at least +125°C, to a PC board with a 0.6mm diameter hole.
For AWG30 wires, a fold back with 10mm strip length is recommended.
2. Temperature range: -55°C to +150°C.

For best results, prepare the cable as shown:



		Raychem THERMOFIT DEVICES		TITLE:		
				PINPAK* PCB TERMINATOR		
Unless otherwise specified dimensions are in millimeters.				DOCUMENT NO.:		
				B-801-15-01		
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		REV:	DATE:	
				4	09-Mar-2020	
DRAWN BY: M. FORONDA	DATE: 22-Mar-1999	ECO: ECO-20-003687	SCALE: NTS	SIZE: A	SHEET: 1 of 1	

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